The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-11. (Canceled)

12. (Currently Amended) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a transistor comprising a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film;

an interlayer insulating film over the transistor;

a wiring formed on the interlayer insulating film, wherein the wiring is connected to an impurity region of the semiconductor film; and

an antenna formed on the interlayer insulating film and in the same layer as the wiring.

13. (Previously Presented) A flexible integrated circuit according to claim 12, wherein the antenna comprises a same material as the wiring.

14. (Previously Presented) A flexible integrated circuit according to claim 12, wherein the antenna comprises a conductive paste.

15.-23. (Canceled)

24. (Currently Amended) A container comprising a flexible integrated circuit capable of performing data transmission wirelessly,

wherein the flexible integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a transistor comprising a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film;

an interlayer insulating film over the transistor;

a wiring provided on the interlayer insulating film; and

an antenna provided on the interlayer insulating film and in the same layer as the wiring.

25. (Previously Presented) A container according to claim 24, wherein the flexible integrated circuit is covered by a label.

26. (Previously Presented) A container according to claim 25, wherein a protective film having a DLC film or a CN film is provided between the flexible integrated circuit and the label.

27. (Previously Presented) A container according to claim 24, wherein the flexible integrated circuit is held between a first label and a second label, and the first label is affixed to the flexible integrated circuit with an adhesive.

28.-62. (Canceled)

63. (Currently Amended) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit disposed over a substrate, the integrated circuit comprising thin film transistors each including an impurity region;

an interlayer insulating film over the thin film transistors; and

an antenna provided on the interlayer insulating film and in the same layer as a wiring connected to the impurity region,

wherein the substrate has a flexibility.

64. (Previously Presented) A flexible integrated circuit according to claim 63 wherein the substrate is a plastic substrate.

65. (Previously Presented) A flexible integrated circuit according to claim 63 wherein each of the thin film transistors includes a semiconductor film comprising silicon.

66. (Previously Presented) A flexible integrated circuit according to claim 63 wherein the antenna is electrically connected to the integrated circuit.

67. (Currently Amended) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit attached to a substrate with an adhesive interposed therebetween, the integrated circuit comprising thin film transistors each including an impurity region;

an interlayer insulating film over the thin film transistors; and

an antenna provided on the interlayer insulating film and in the same layer as a wiring connected to the impurity region,

wherein the substrate has a flexibility.

68. (Previously Presented) A flexible integrated circuit according to claim 67 wherein the substrate is a plastic substrate.

69. (Previously Presented) A flexible integrated circuit according to claim 67 wherein each of the thin film transistors includes a semiconductor film comprising silicon.

70. (Previously Presented) A flexible integrated circuit according to claim 67 wherein the antenna is electrically connected to the integrated circuit.

71. (Currently Amended) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit disposed over a substrate, the integrated circuit comprising thin film transistors each including an impurity region;

an interlayer insulating film over the thin film transistors;

an antenna provided on the interlayer insulating film and in the same layer as a wiring connected to the impurity region; and

a protective film covering the antenna,

wherein the substrate has a flexibility.

72. (Previously Presented) A flexible integrated circuit according to claim 71 wherein the substrate is a plastic substrate.

73. (Previously Presented) A flexible integrated circuit according to claim 71 wherein each of the thin film transistors includes a semiconductor film comprising silicon.

74. (Previously Presented) A flexible integrated circuit according to claim 71 further comprising a wiring electrically connected to the integrated circuit wherein the wiring and the antenna are formed on a same surface.

75. (Currently Amended) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit attached to a substrate with an adhesive interposed therebetween, the integrated circuit comprising thin film transistors each including an impurity region;

an interlayer insulating film over the thin film transistors;

an antenna provided on the interlayer insulating film and in the same layer as a wiring connected to the impurity region; and

a protective film covering the antenna,

wherein the substrate has a flexibility.

76. (Previously Presented) A flexible integrated circuit according to claim 75 wherein the substrate is a plastic substrate.

77. (Previously Presented) A flexible integrated circuit according to claim 75 wherein each of the thin film transistors includes a semiconductor film comprising silicon.

78. (Previously Presented) A flexible integrated circuit according to claim 75 further comprising a wiring electrically connected to the integrated circuit wherein the wiring and the antenna are formed on a same surface.

79. (Currently Amended) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit including a memory disposed over a substrate, the integrated circuit comprising thin film transistors each including an impurity region;

an interlayer insulating film over the thin film transistors; and

an antenna provided on the interlayer insulating film and in the same layer as a wiring connected to the impurity region,

wherein the substrate has a flexibility.

80. (Previously Presented) A flexible integrated circuit according to claim 79 wherein the substrate is a plastic substrate.

81. (Previously Presented) A flexible integrated circuit according to claim 79 wherein each of the thin film transistors includes a semiconductor film comprising silicon.

82. (Previously Presented) A flexible integrated circuit according to claim 79 wherein the antenna is electrically connected to the integrated circuit.

83. (Previously Presented) A flexible integrated circuit according to claim 79 wherein the memory is a rewritable memory.

84. (Previously Presented) A flexible integrated circuit according to claim 79 wherein the integrated circuit is attached to the substrate with an adhesive interposed therebetween.

85.-88. (Canceled)

89. (Previously Presented) A flexible integrated circuit according to claim 12, wherein the interlayer insulating film comprises an organic material.

90. (Previously Presented) A container according to claim 24, wherein the interlayer insulating film comprises an organic material.

91. (Previously Presented) A flexible integrated circuit according to claim 63, wherein the interlayer insulating film comprises an organic material.

92. (Previously Presented) A flexible integrated circuit according to claim 67, wherein the interlayer insulating film comprises an organic material.

93. (Previously Presented) A flexible integrated circuit according to claim 71, wherein the interlayer insulating film comprises an organic material.

94. (Previously Presented) A flexible integrated circuit according to claim 75, wherein the interlayer insulating film comprises an organic material.

95. (Previously Presented) A flexible integrated circuit according to claim 79, wherein the interlayer insulating film comprises an organic material.

96. (Previously Presented) A flexible integrated circuit according to claim 12, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

97. (Previously Presented) A container according to claim 24, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

98. (Previously Presented) A flexible integrated circuit according to claim 63, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

99. (Previously Presented) A flexible integrated circuit according to claim 67, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

100. (Previously Presented) A flexible integrated circuit according to claim 71, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

101. (Previously Presented) A flexible integrated circuit according to claim 75, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

102. (Previously Presented) A flexible integrated circuit according to claim 79, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

103. (Currently Amended) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

a substrate;

an adhesive over the substrate;

an insulating film over the substrate with the adhesive therebetween;

a transistor comprising a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film;

an interlayer insulating film over the transistor;

a wiring formed on the interlayer insulating film, wherein the wiring is connected to an impurity region of the semiconductor film; and

an antenna formed on the interlayer insulating film and in the same layer as the wiring.

104. (Previously Presented) A flexible integrated circuit according to claim 103, wherein the antenna comprises a same material as the wiring.

105. (Previously Presented) A flexible integrated circuit according to claim 103, wherein the antenna comprises a conductive paste.

106. (Previously Presented) A flexible integrated circuit according to claim 103, wherein the interlayer insulating film comprises an organic material.

107. (Previously Presented) A flexible integrated circuit according to claim 103, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.

108. (Currently Amended) A container comprising a flexible integrated circuit capable of performing data transmission wirelessly,

wherein the flexible integrated circuit comprises:

a substrate;

an adhesive over the substrate;

an insulating film over the substrate with the adhesive therebetween;

a transistor comprising a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film;

an interlayer insulating film over the transistor;

a wiring provided on the interlayer insulating film; and

an antenna provided on the interlayer insulating film and in the same layer as the wiring.

109. (Previously Presented) A container according to claim 108, wherein the flexible integrated circuit is covered by a label.

110. (Currently Amended) A container according to claim [[108]] 109, wherein a protective film having a DLC film or a CN film is provided between the flexible integrated circuit and the label.

111. (Previously Presented) A container according to claim 108, wherein the flexible integrated circuit is held between a first label and a second label, and the first label is affixed to the flexible integrated circuit with an adhesive.

112. (Previously Presented) A container according to claim 108, wherein the interlayer insulating film comprises an organic material.

113. (Previously Presented) A container according to claim 108, wherein the antenna is formed in a depressed portion formed in the interlayer insulating film.